

ABSTRACT OF THE DISCLOSURE

LIQUID PROCESSING METHOD, LIQUID PROCESSING APPARATUS AND
RECORDING MEDIUM

There are provided a liquid processing method, a liquid processing apparatus and a recording medium for liquid processing which can enhance the uniformity of the coating state of a processing liquid on a substrate. A coating unit U1 includes a rotary holder 20 for rotating a wafer W, a nozzle 32 for supplying a processing liquid R onto a surface Wa of the wafer W, and a controller 60 for controlling the position of the nozzle 32 with respect to the wafer W. A liquid processing method includes: starting the supply of the processing liquid R to the surface Wa of the wafer W at an eccentric position at a distance from the center CL1 of rotation of the wafer W, and moving the position on the wafer W to which the processing liquid R is supplied toward the center CL1 of rotation of the wafer W while rotating the wafer W at a first rotational speed ω_1 ; and, after the processing liquid supply position has reached the center CL1 of rotation of the wafer W, rotating the wafer W at a second rotational speed ω_2 which is higher than the first rotational speed ω_1 , thereby allowing the processing liquid R to spread toward the periphery of the wafer W.

FIG. 4